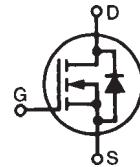


HiPerFET™ Power MOSFET

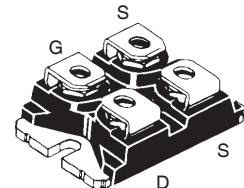
IXFN 80N50Q2

N-Channel Enhancement Mode
Avalanche Rated, Low Q_g , Low Intrinsic R_G
High dV/dt, Low t_{rr}

$V_{DSS} = 500 \text{ V}$
 $I_{D25} = 80 \text{ A}$
 $R_{DS(on)} = 60 \text{ m}\Omega$
 $t_{rr} \leq 250 \text{ ns}$



miniBLOC, SOT-227 B (IXFN)
 E153432



G = Gate D = Drain
S = Source

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	500		V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1 \text{ M}\Omega$	500		V
V_{GS}	Continuous	± 30		V
V_{GSM}	Transient	± 40		V
I_{D25}	$T_c = 25^\circ\text{C}$	80		A
I_{DM}	$T_c = 25^\circ\text{C}$, pulse width limited by T_{JM}	320		A
I_{AR}	$T_c = 25^\circ\text{C}$	80		A
E_{AR}	$T_c = 25^\circ\text{C}$	60		mJ
E_{AS}	$T_c = 25^\circ\text{C}$	5.0		J
dV/dt	$I_s \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$ $T_J \leq 150^\circ\text{C}$, $R_G = 2 \Omega$	20		V/ns
P_D	$T_c = 25^\circ\text{C}$	890		W
T_J		-55 ... +150		$^\circ\text{C}$
T_{JM}		150		$^\circ\text{C}$
T_{stg}		-55 ... +150		$^\circ\text{C}$
V_{ISOL}	50/60 Hz, RMS, $t = 1$ minute	2500		V
M_d	Mounting torque Terminal connection torque	1.5/13	Nm/lb.in.	
Weight		30		g

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 1 \text{ mA}$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 8 \text{ mA}$	2.5		5.0 V
I_{GSS}	$V_{GS} = \pm 30 \text{ V}$, $V_{DS} = 0$			$\pm 200 \text{ nA}$
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$		100 μA 5 mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 0.5 \cdot I_{D25}$ Note 1			60 m Ω

Features

- Double metal process for low gate resistance
- miniBLOC, with Aluminium nitride isolation
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- Fast intrinsic Rectifier

Applications

- DC-DC converters
- Switched-mode and resonant-mode power supplies
- DC choppers
- Pulse generators

Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values			
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.	max.
I_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$	Note 1	50	65	S
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	10500		pF	
		1610		pF	
		300		pF	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1 \Omega$ (External)	29		ns	
		25		ns	
		60		ns	
		11		ns	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$	260		nC	
		65		nC	
		125		nC	
R_{thJC}			0.14	K/W	
R_{thCK}		0.05		K/W	

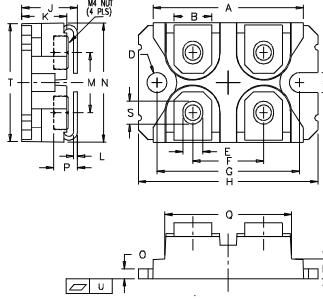
Source-Drain Diode

Characteristic Values
($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Test Conditions	min.	typ.	max.
I_s	$V_{GS} = 0 \text{ V}$		80	A
I_{SM}	Repetitive; pulse width limited by T_{JM}		320	A
V_{SD}	$I_F = I_s, V_{GS} = 0 \text{ V}$, Note 1		1.5	V
t_{rr} Q_{RM} I_{RM}	$I_F = 25 \text{ A}$ $-di/dt = 100 \text{ A}/\mu\text{s}$ $V_R = 100 \text{ V}$		250	ns
		1.2		μC
		8		A

Note: 1. Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2 \%$

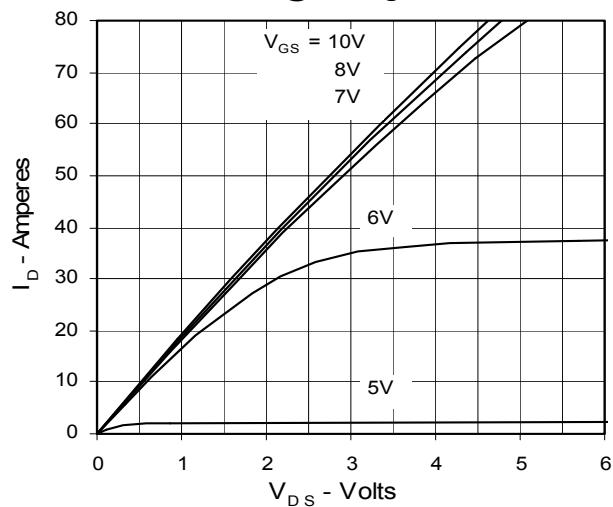
miniBLOC, SOT-227 B Outline



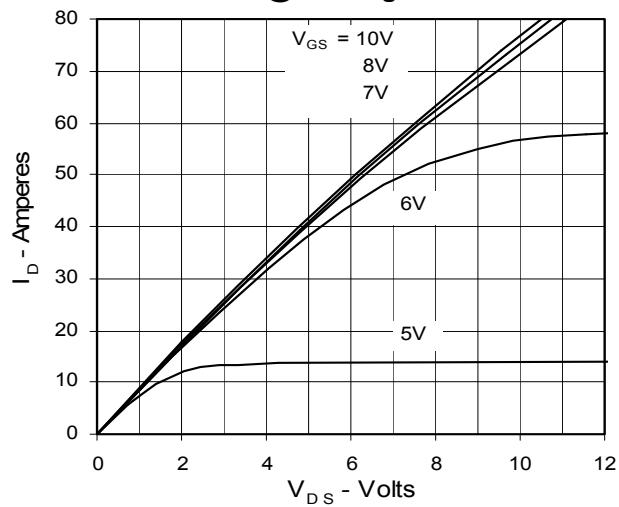
M4 screws (4x) supplied

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	38.00	38.23	1.496	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.76	0.84	0.030	0.033
M	12.60	12.85	0.496	0.506
N	25.15	25.42	0.990	1.001
O	1.98	2.13	0.078	0.084
P	4.95	5.97	0.195	0.235
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.174
S	4.72	4.85	0.186	0.191
T	24.59	25.07	0.968	0.987
U	-0.05	0.1	-0.002	0.004

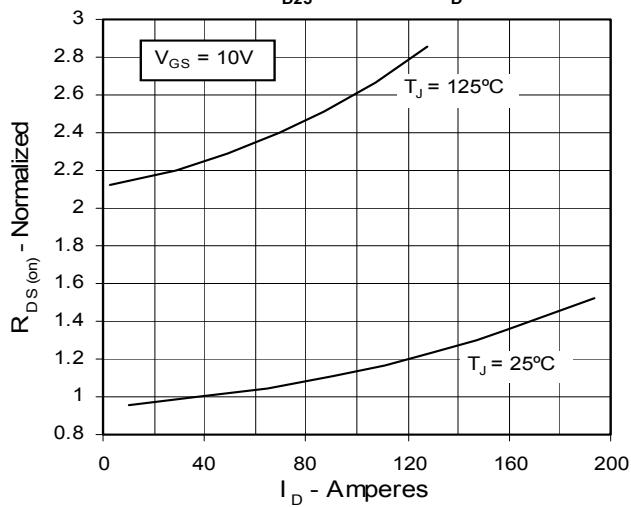
**Fig. 1. Output Characteristics
@ 25 Deg. C**



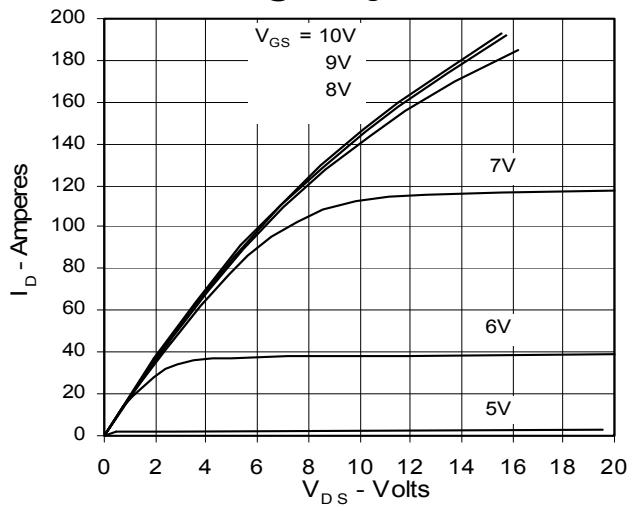
**Fig. 3. Output Characteristics
@ 125 Deg. C**



**Fig. 5. $R_{DS(on)}$ Normalized to
0.5 I_{D25} Value vs. I_D**



**Fig. 2. Extended Output Characteristics
@ 25 deg. C**



**Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value
vs. Junction Temperature**

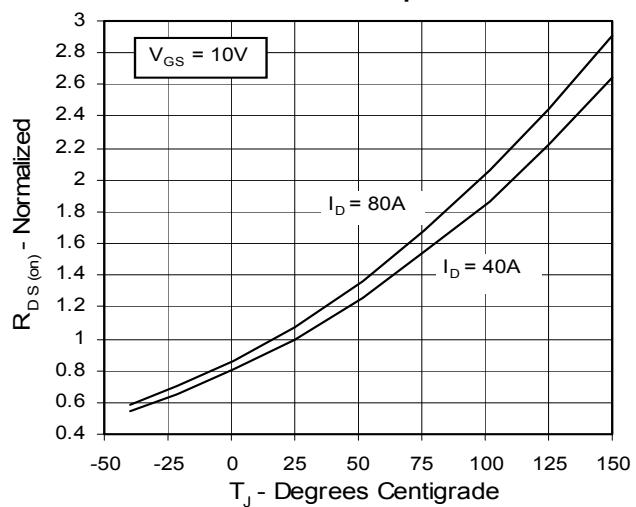


Fig. 6. Drain Current vs. Case Temperature

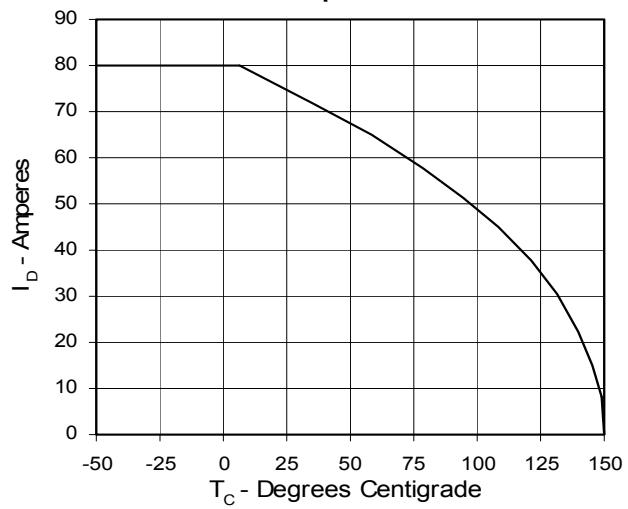
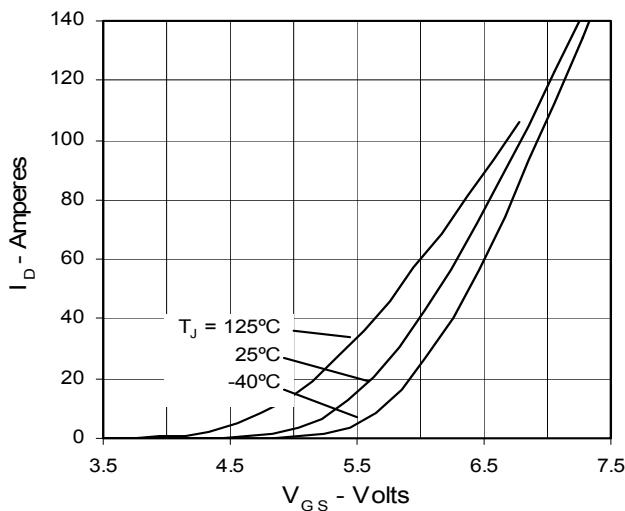
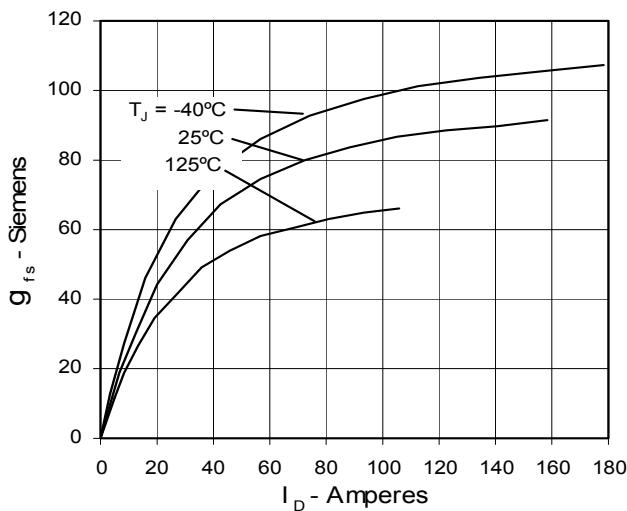
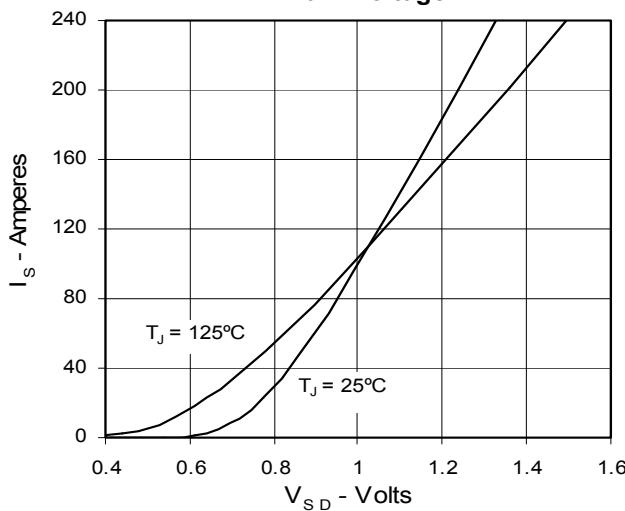
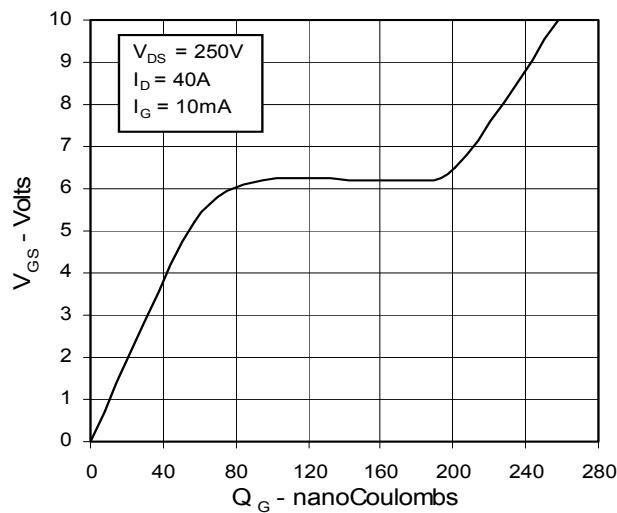
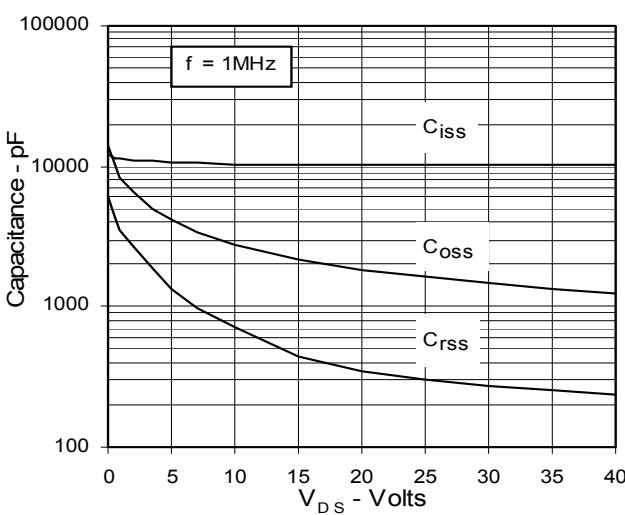


Fig. 7. Input Admittance

Fig. 8. Transconductance

Fig. 9. Source Current vs. Source-To-Drain Voltage

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Maximum Transient Thermal Resistance
